

1150 Thermal pads

The thermal conductivity of the interface material has a significant impact on its thermal performance. The high thermal conductivity guarantees sufficient heat transfer, resulting in a better cooling solution and the desired heat dissipation.

Properties

- Good insulation properties
- Heat-conducting
- Good compressibility
- Flexible
- Environmentally friendly

Benefits

- Smooth surface
- Very good thermal transfer properties even at very low contact pressure
- Low hardness
- High self-adhesion
- UL listed
- Thickness 0.01 to 8 mm

This film is especially suitable for high-power applications. It has excellent thermal and electrical properties. Thanks to its good performance, the material can be used reliably in densely packed electronic applications.

Applications

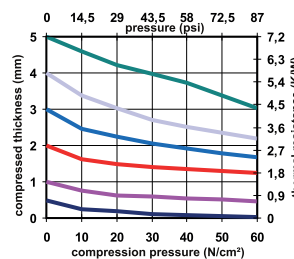
- RD-RAM Memory Module
- Heat pipe thermal solutions
- Automotive engine
- Control units
- Plasma supply console

Properties

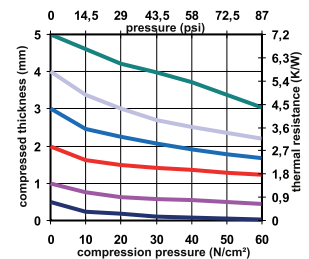
Properties	Unit	1150-202	1150-212
Color		grey	grey
Thermal Properties			
Thermal resistance R^{th}	K/W	0.9	0.9
Thermal impedance R_{ti}	$^{\circ}\text{Cmm}^2/\text{W Kin}^2/\text{W}$	357 / 0.55	357 / 0.55
Thermal conductivity λ	W/mK	1.4	1.4
Electrical Properties			
Breakdown Voltage $U_{d,ac}$	KV	2.5	2.0
Dielectric breakdown $E_{d,ac}$	KV/mm	5	4
Volume Resistivity R_{ti}	Ωcm	2.7×10^{12}	1.2×10^{15}
Dielectric loss factor $\tan \delta$	1	6.0×10^{-3}	4.5×10^{-4}
Dielectric Constant ϵ_r	1	4.2	2.68
Mechanical Properties			
Measured Thickness ($\pm 10\%$)	mm	0.5 to 5.0	0.5 to 5.0
Hardness	Shore 00	20 - 30	25 - 35
Youngs Modulus	N/cm ²	47	39
Physical Properties			
Density	g/cm ³	1.46	1.46
Application temperature	$^{\circ}\text{C}$	-60 to +200	-60 to +200
TML	Ma.-%	< 0.5	< 0.25
Flame rating	UL	94V-0	-
Possible thickness	mm	0.5 - 5.0	0.5 - 5.0

Compression of 1150 Thermal pads

1150-202



1150-212



The information on this sheet has been compiled from the results of various test data. This publication however, cannot be considered as a commitment or as a written guarantee.

The information presented cannot replace the necessity of serious testing of the product in its actual application